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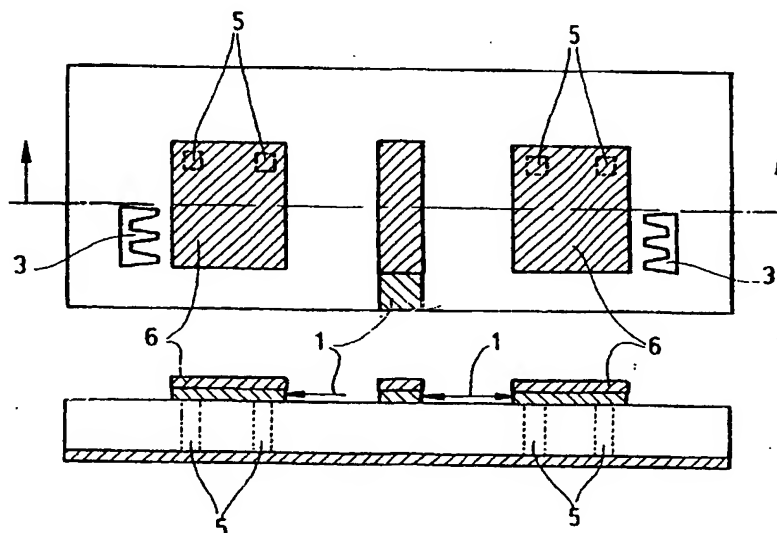
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(54) Title: INTEGRATED CIRCUIT AND METHOD FOR MANUFACTURING SAME



(57) Abstract: The invention relates to an integrated circuit having at least one microstrip line and at least one port, and to a method for manufacturing same, these being able to be used, in particular, for test passes for development purposes during chip production and also during chip manufacture. The invention provides for at least some of the ports and/or microstrip lines (1) in the integrated circuit to have a removable, reflection-free termination which is integrated on the chip. The inventive method provides for an integrated circuit to be produced in a first step, with at least some of the ports and/or microstrip lines (1) in the integrated circuit being provided with a removable, reflection-free termination which is integrated on the chip, and in a second step for this termination to be removed from a prescribable selection of the ports and/or microstrip lines (1) provided with the removable, reflection-free termination which is integrated on the chip.